



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-23
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ACST830-8GTR	7TI8*A6C088C	A	SHENZHEN B/E	2015-09-23
Amount		UoM	Unit type	ST ECOPACK Grade
1380.00		mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	D2PAK DOUBLE TRACK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7T18*A6C088C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	4.420	mg	supplier	die	Silicon (Si)	7440-21-3		4.257	mg	963131	3086
				supplier	metallization	Aluminium (Al)	7429-90-5		0.070	mg	15834	51
				supplier	Passivation	Silicon Oxide	7631-86-9		0.023	mg	5202	17
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.023	mg	5202	17
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	679	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1810	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.036	mg	8143	26
				supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	563433
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	474
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	733
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	5.143	mg	954883	3727
Soft solder	Solder	5.386	mg	supplier	solder	Silver (Ag)	7440-22-4		0.135	mg	25065	98
				supplier	solder	Tin (Sn)	7440-31-5		0.108	mg	20052	78
				supplier	wire	Aluminium (Al)	7429-90-5		0.322	mg	1000000	233
Encapsulation	Other Organic Materials	587.816	mg	supplier	mold compound	Silica, vitreous	60676-86-0		473.779	mg	805999	343318
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		41.147	mg	70000	29817
				supplier	mold compound	Phenol resin	9003-35-4		23.513	mg	40001	17038
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		35.269	mg	60000	25557
				supplier	mold compound	Antimony Trioxide	1309-64-4		7.054	mg	12000	5112
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		4.115	mg	7000	2982
				supplier	mold compound	Carbon black	1333-86-4		2.939	mg	5000	2130
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804